

Linear Flash Intel/Sharp S5 Memory Card 2MB, 4MB, 8MB, 16MB

General Description

CardPro™ 2000 Intel/sharp S5 Flash memory cards offer high density linear Flash solid state storage solutions for code and data storage, high performance disk emulation and execute in place (XIP) applications in mobile PC and dedicated (embedded) equipment.

CardPro™ 2000 Intel/Sharp S5 Flash cards conform to PCMCIA international standard.

The card's control logic provides the system interface and controls the internal Flash memories. Card can be read/written in byte-wide or word-wide mode which allows for flexible integration into various systems. Combined with file management software, such as Flash Translation Layer (FTL), **CardPro™ 2000** Intel/Sharp S5 Flash cards provide removable high-performance disk emulation.

CardPro™ 2000 Intel/Sharp S5 Flash cards offers low power modes controlled by registers. Standard cards contain separate 2kB EEPROM memory for Card Information Structure (CIS) which can be used for easy identification of card characteristics.

CardPro™ 2000 Intel/Sharp S5 is based on Intel/Sharp 28F016S5 Flash memories.

Note: Standard options include attribute memory. Cards without attribute memory are available. Cards are also available with or without a hardware write protect switch.

Architecture Overview

CardPro™ 2000 Intel/Sharp S5 is designed to support from qty 2 to 8 of 16Mb devices, providing a range of density options. Cards are based on the 28F016S5 (16Mb) devices for 5V only applications. Devices code for the 28F016S5 is AAH. Cards utilizing the 16Mb components provide densities of 2MB, 4MB, 8MB, 16MB.

In support of the PC Card 95 standard for word wide access devices are paired. Therefore, the Flash array is structured in 64K word (128kBytes) blocks. Write, read and block erase operations can be performed as either a word or byte wide operation. By multiplexing A0, CE1# and CE2#, 8-bit hosts can access all data on data lines DQ0 - DQ7.

CardPro™ 2000 Intel/Sharp S5Flash cards supports the following PCMCIA compatible register functions: Soft Reset via the Configuration Option Register, Power Down (sleep mode) via the Configuration and Status Register and monitoring of Ready/Busy, Soft Reset and Power Down via the Card Status Register.

CardPro™ 2000 Intel/Sharp S5 Flash cards conform with the PC Card Standard (PCMCIA) and JEIDA 4.2, providing electrical and physical compatibility. The PC Card form factor offers an industry standard pinout and mechanical outline, allowing density upgrades without system design changes.

Standard cards are shipped with **CardPro™ 2000** Linear Flash Logo. Cards are also available with custom labeling using only primary colours and simple artwork.

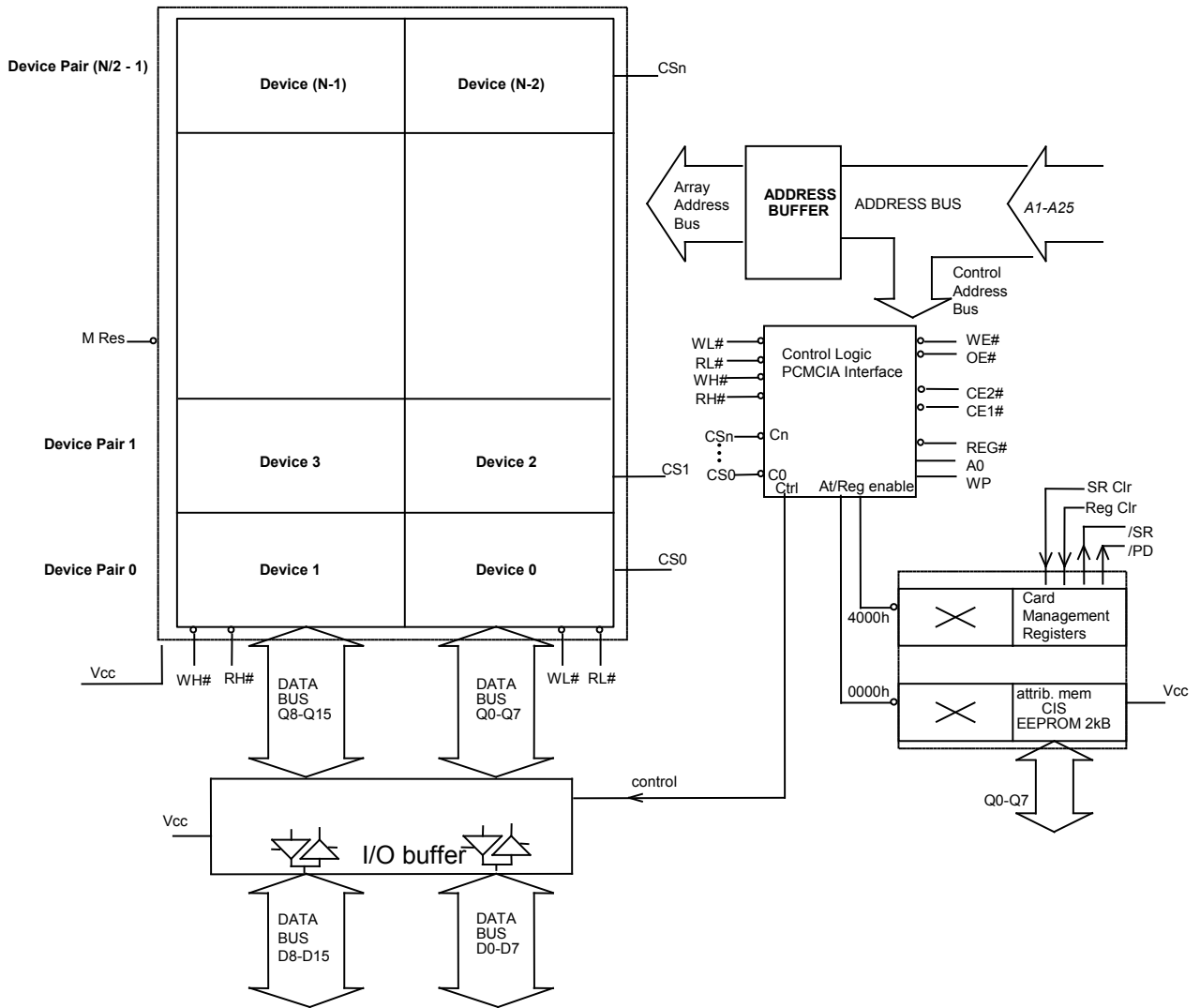
Features

- Low cost High Density Linear Flash Card
- Supports 5V only systems
- Based on Intel/Sharp FlashFile Devices
- Fast Read Performance
 - 90ns Access Time
- x8 / x16 Data Interface
- High Performance Random Writes
 - 8µs Typical Word Write Time
- Automated Write and Erase Algorithms
 - Command User Interface
- 100,000 Erase Cycles per Block
- 64K word symmetrical Block Architecture
- PC Card Standard Type I Form Factor

PCMCIA Linear Flash Memory Card

Block Diagram

| Device type | Manuf ID | Device ID |
|-------------|-----------------|-----------------|
| 28F016S5 | 89 _H | AA _H |



Registers in Attribute Memory Space

| ADDRESS | Register NAME |
|---------|-------------------------------|
| 4100h | Status Reg. |
| 4002h | Config. and Status Reg. |
| 4000h | Configuration Option Register |

COR

Configuration Option Register: ADRS=4000h Write Only

| | | | | | | | |
|------|------|-----------------------|----|----|----|----|----|
| SRES | LREQ | -Configuration Index- | | | | | |
| D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |

- D7 Soft Reset, active High
- 1 = Reset State
- 0 = End Reset State
- D6 LevelReq (not supported)
- D5-D0 Configuration index (not supported)

CSR

Configuration Status Register: ADRS=4002h Write Only

| | | | | | | | |
|---------------|----|----|------|----|---------------|----|----|
| not supported | | | PDwn | | not supported | | |
| D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |

- D2 Power Down; active High
- 1=Place all memory devices in power down mode
- 0=normal operation Power On default=0

SR

Status Register: ADRS=4100h Read Only

| | | | | | | | |
|---------------|----|--------|------|----|---------------|----|-------|
| not supported | | SReset | PDwn | | not supported | | R/BSY |
| D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |

- D5 Represents the state of SRESET bit in COR (4000h)
- 1=Reset
- 0=Normal operation
- Power On default D5=0
- D3 Represents the state of Power Down bit (D2) in CSR (4002h)
- 1=Power Down
- D0 Reflects the card's Ready/Busy signal (pin 16) driven by memory components Ready/Busy outputs. This bit allows software polling of the card's Ready/Busy status.
- 1=Ready

Pinout

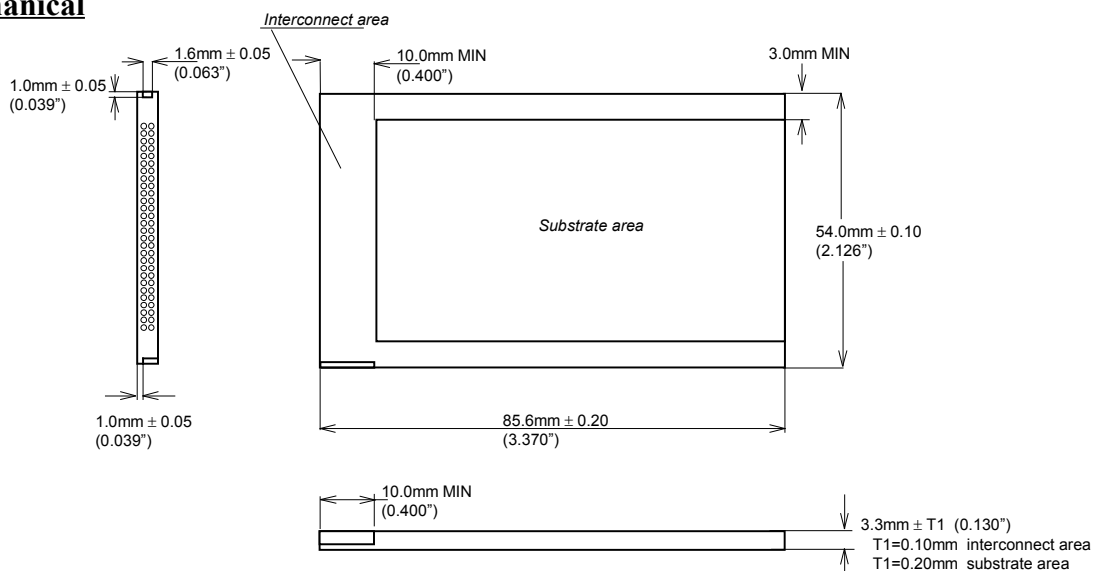
| Pin | Signal name | I/O | Function | Active |
|-----|-------------|-----|----------------|--------|
| 1 | GND | | Ground | |
| 2 | DQ3 | I/O | Data bit 3 | |
| 3 | DQ4 | I/O | Data bit 4 | |
| 4 | DQ5 | I/O | Data bit 5 | |
| 5 | DQ6 | I/O | Data bit 6 | |
| 6 | DQ7 | I/O | Data bit 7 | |
| 7 | CE1# | I | Card enable 1 | LOW |
| 8 | A10 | I | Address bit 10 | |
| 9 | OE# | I | Output enable | LOW |
| 10 | A11 | I | Address bit 11 | |
| 11 | A9 | I | Address bit 9 | |
| 12 | A8 | I | Address bit 8 | |
| 13 | A13 | I | Address bit 13 | |
| 14 | A14 | I | Address bit 14 | |
| 15 | WE# | I | Write Enable | LOW |
| 16 | RDY/BSY# | O | Ready/Busy | LOW |
| 17 | Vcc | | Supply Voltage | |
| 18 | Vpp1 | | Prog. Voltage | N.C. |
| 19 | A16 | I | Address bit 16 | |
| 20 | A15 | I | Address bit 15 | |
| 21 | A12 | I | Address bit 12 | |
| 22 | A7 | I | Address bit 7 | |
| 23 | A6 | I | Address bit 6 | |
| 24 | A5 | I | Address bit 5 | |
| 25 | A4 | I | Address bit 4 | |
| 26 | A3 | I | Address bit 3 | |
| 27 | A2 | I | Address bit 2 | |
| 28 | A1 | I | Address bit 1 | |
| 29 | A0 | I | Address bit 0 | |
| 30 | DQ0 | I/O | Data bit 0 | |
| 31 | DQ1 | I/O | Data bit 1 | |
| 32 | DQ2 | I/O | Data bit 2 | |
| 33 | WP | O | Write Potect | HIGH |
| 34 | GND | | Ground | |

| Pin | Signal name | I/O | Function | Active |
|-----|-------------|-----|---------------------|---------|
| 35 | GND | | Ground | |
| 36 | CD1# | O | Card Detect 1 | LOW |
| 37 | DQ11 | I/O | Data bit 11 | |
| 38 | DQ12 | I/O | Data bit 12 | |
| 39 | DQ13 | I/O | Data bit 13 | |
| 40 | DQ14 | I/O | Data bit 14 | |
| 41 | DQ15 | I | Data bit 15 | |
| 42 | CE2# | I | Card Enable 2 | LOW |
| 43 | VS1 | O | Voltage Sense 1 | N.C. |
| 44 | RFU | | Reserved | |
| 45 | RFU | | Reserved | |
| 46 | A17 | I | Address bit 17 | |
| 47 | A18 | I | Address bit 18 | |
| 48 | A19 | I | Address bit 19 | |
| 49 | A20 | I | Address bit 20 | 2MB(3) |
| 50 | A21 | I | Address bit 21 | 4MB(3) |
| 51 | Vcc | | Supply Voltage | |
| 52 | Vpp2 | | Prog. Voltage | N.C. |
| 53 | A22 | I | Address bit 22 | 8MB(3) |
| 54 | A23 | I | Address bit 23 | 16MB(3) |
| 55 | A24 | I | Address bit 24 | N.C. |
| 56 | A25 | I | Address bit 25 | N.C. |
| 57 | VS2 | O | Voltage Sense 2 | N.C. |
| 58 | RST | I | Card Reset | HIGH |
| 59 | Wait# | O | Extended Bus cycle | Low(2) |
| 60 | RFU | | Reserved | |
| 61 | REG# | I | Attrib Mem Select | |
| 62 | BVD2 | O | Bat. Volt. Detect 2 | (2) |
| 63 | BVD1 | O | Bat. Volt. Detect 1 | (2) |
| 64 | DQ8 | I/O | Data bit 8 | |
| 65 | DQ9 | I/O | Data bit 9 | |
| 66 | DQ10 | O | Data bit 10 | |
| 67 | CD2# | O | Card Detect 2 | LOW |
| 68 | GND | | Ground | |

Notes:

- 1.RDY/BSY signal is an "Open drain" type output.
2. Wait#, BVD1 and BVD2 are driven high for compatibility.
3. Shows density for which specified address bit is MSB. Higher order address bits are no connects (ie 4MB A21 is MSB, A22 - A25 are NC).

Mechanical



Card Signal Description

| Symbol | Type | Name and Function |
|------------|--------------|--|
| A0 - A25 | INPUT | ADDRESS INPUTS: A0 through A23 enable direct addressing of up to 16MB of memory on the card. Signal A0 is not used in word access mode. A23 is the most significant bit |
| DQ0 - DQ15 | INPUT/OUTPUT | DATA INPUT/OUTPUT: DQ0 THROUGH DQ15 constitute the bi-directional databus. DQ15 is the MSB. |
| CE1#, CE2# | INPUT | CARD ENABLE 1 AND 2: CE1# enables even byte accesses, CE2# enables odd byte accesses. Multiplexing A0, CE1# and CE2# allows 8-bit hosts to access all data on DQ0 - DQ7. |
| OE# | INPUT | OUTPUT ENABLE: Active low signal gating read data from the memory card. |
| WE# | INPUT | WRITE ENABLE: Active low signal gating write data to the memory card. |
| RDY/BSY# | OUTPUT | READY/BUSY OUTPUT: Indicates status of internally timed erase or program algorithms. A high output indicates that the card is ready to accept accesses. A low output indicates that one or more devices in the memory card are busy with internally timed erase or write activities. |
| CD1#, CD2# | OUTPUT | CARD DETECT 1 and 2: Provide card insertion detection. These signals are internally connected to ground on the card. The host shall monitor these signals to detect card insertion (pulled-up on host side). |
| WP | OUTPUT | WRITE PROTECT: Write protect reflects the status of the Write Protect switch on the memory card. WP set to high = write protected, providing internal hardware write lockout to the Flash array. If card does not include optional write protect switch, this signal will be pulled low internally indicating write protect = "off". |
| VPP1, VPP2 | N.C. | PROGRAM/ERASE POWER SUPPLY: Provides programming voltages for card (12V). Not connected for 5V only card. |
| VCC | | CARD POWER SUPPLY: (5.0V). |
| GND | | CARD GROUND |
| REG# | INPUT | ATTRIBUTE MEMORY SELECT : Active low signal, enables access to Attribute Memory Plane, occupied by Card Information Structure and Card Registers. |
| RST | INPUT | RESET: Active high signal for placing card in Power-on default state. Reset can be used as a Power-Down signal for the memory array. |
| WAIT# | OUTPUT | WAIT: This signal is pulled high internally for compatibility. No wait states are generated. |
| BVD1, BVD2 | OUTPUT | BATTERY VOLTAGE DETECT: These signals are pulled high to maintain SRAM card compatibility. |
| VS1, VS2 | OUTPUT | VOLTAGE SENSE: Notifies the host socket of the card's VCC requirements. VS1 and VS2 are open to indicate a 5V card . |
| RFU | | RESERVED FOR FUTURE USE |
| N.C. | | NO INTERNAL CONNECTION TO CARD: pin may be driven or left floating |

Functional Truth Table

READ function

| Function Mode | /CE2 | /CE1 | A0 | /OE | /WE |
|-----------------------|------|------|----|-----|-----|
| Standby Mode | H | H | X | X | X |
| Byte Access (8 bits) | H | L | L | L | H |
| | H | L | H | L | H |
| Word Access (16 bits) | L | L | X | L | H |
| Odd-Byte Only Access | L | H | X | L | H |

Common Memory

| /REG | D15-D8 | D7-D0 |
|------|----------|-----------|
| X | High-Z | High-Z |
| H | High-Z | Even-Byte |
| H | High-Z | Odd-Byte |
| H | Odd-Byte | Even-Byte |
| H | Odd-Byte | High-Z |

Attribute Memory

| /REG | D15-D8 | D7-D0 |
|------|-----------|-----------|
| X | High-Z | High-Z |
| L | High-Z | Even-Byte |
| L | High-Z | Not Valid |
| L | Not Valid | Even-Byte |
| L | Not Valid | High-Z |

WRITE function

| Function Mode | /CE2 | /CE1 | A0 | /OE | /WE |
|-----------------------|------|------|----|-----|-----|
| Standby Mode | H | H | X | X | X |
| Byte Access (8 bits) | H | L | L | H | L |
| | H | L | H | H | L |
| Word Access (16 bits) | L | L | X | H | L |
| Odd-Byte Only Access | L | H | X | H | L |

| /REG | D15-D8 | D7-D0 |
|------|----------|-----------|
| X | X | X |
| H | X | Even-Byte |
| H | X | Odd-Byte |
| H | Odd-Byte | Even-Byte |
| H | Odd-Byte | X |

| /REG | D15-D8 | D7-D0 |
|------|--------|-----------|
| X | X | X |
| L | X | Even-Byte |
| L | X | X |
| L | X | Even-Byte |
| L | X | X |

Absolute Maximum Ratings ⁽¹⁾

| | |
|--|-------------------|
| Operating Temperature TA (ambient) Commercial | 0°C to +60 °C |
| Storage Temperature Commercial | -30°C to +80 °C |
| Voltage on any pin relative to VSS | -0.5V to VCC+0.5V |
| VCC supply Voltage relative to VSS | -0.5V to +7.0V |

Note:

(1) Stress greater than those listed under "Absolute Maximum ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at these or any other conditions greater than those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Characteristics ⁽¹⁾

| Symbol | Parameter | Density (Mbytes) | Notes | Typ ⁽³⁾ | Max | Units | Test Conditions |
|-------------------------|---------------------|------------------|-------|--------------------|-----|-------|---|
| I _{CCR} | VCC Read Current | All | | | 35 | mA | VCC = VCCmax t _{cycle} = 150ns, CMOS levels |
| I _{CCW} | VCC Program Current | All | | | 75 | mA | |
| I _{CC E} | VCC Erase Current | All | | | 100 | mA | |
| I _{CCS} (CMOS) | VCC Standby Current | 2MB | 2 | 60 | | μA | VCC = VCCmax Control Signals = VCC Reset = VSS, CMOS levels |
| | | 4MB | | 60 | | | |
| | | 16MB | | 180 | | | |

CMOS Test Conditions: VCC = 5V ± 5%, VIL = VSS ± 0.2V, VIH = VCC ± 0.2V

Notes:

1. All currents are RMS values unless otherwise specified. ICCR, ICCW and ICCE are based on Byte wide operations. For 16 bit operation values are double.
2. Control Signals: CE₁#, CE₂#, OE#, WE#, REG#.
3. Typical: VCC = 5V, T = +25C.

| Symbol | Parameter | Notes | Min | Max | Units | Test Conditions |
|------------------|--------------------------------|-------|---------|---------|-------|-----------------------------------|
| I _{LI} | Input Leakage Current | 1 | | ±20 | μA | VCC = VCCMAX Vin = VCC or VSS |
| I _{LO} | Output Leakage Current | 1 | | ±20 | μA | VCC = VCCMAX Vout = VCC or VSS |
| V _{IL} | Input Low Voltage | 1 | 0 | 0.8 | V | |
| V _{IH} | Input High Voltage | 1 | 0.7VCC | VCC+0.5 | V | |
| V _{OL} | Output Low Voltage | 1 | | 0.4 | V | IOL = 3.2mA |
| V _{OH} | Output High Voltage | 1 | VCC-0.4 | VCC | V | IOH = -2.0mA |
| V _{LKO} | VCC Erase/Program Lock Voltage | 1 | 2.0 | | V | |

Notes:

1. Values are the same for byte and word wide modes for all card densities.
2. Exceptions: Leakage currents on CE1#, CE2#, OE#, REG# and WE# will be < 500 μA when VIN = GND due to internal pull-up resistors. Leakage currents on RST will be <150μA when VIN=VCC due to internal pull-down resistor.

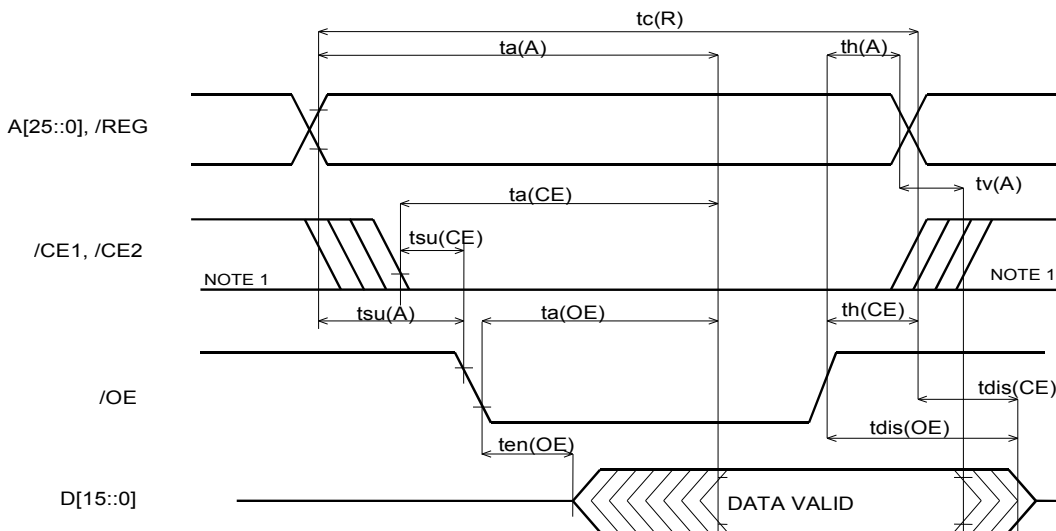
AC Characteristics

Read Timing Parameters

| SYMBOL (PCMCIA) | Parameter | 90ns | | Unit |
|--------------------|---|------|-----|------|
| | | Min | Max | |
| $t_{c(R)}$ | Read Cycle Time | 90 | | ns |
| $t_{a(A)}$ | Address Access Time | | 90 | ns |
| $t_{a(CE)}$ | Card Enable Access Time | | 90 | ns |
| $t_{a(OE)}$ | Output Enable Access Time | | 75 | ns |
| $t_{su(A)}$ | Address Setup Time | | 20 | ns |
| $t_{su(CE)}$ | Card Enable Setup Time | | 0 | ns |
| $t_h(A)$ | Address Hold Time | | 20 | ns |
| $t_h(CE)$ | Card Enable Hold Time | | 20 | ns |
| $t_v(A)$ | Output Hold from Address Change | | 0 | ns |
| $t_{dis(CE)}$ | Output Disable Time from CE# | | 75 | ns |
| $t_{dis(OE)}$ | Output Disable Time from OE# | | 75 | ns |
| $t_{en(CE)}$ | Output Enable Time from CE# | 5 | | ns |
| $t_{en(OE)}$ | Output Enable Time from OE# | 5 | | ns |
| $t_{rec(RSR)}$ | Power Down recovery to Output Delay. VCC = 5V | | 500 | ns |

Note: AC timing diagrams and characteristics are guaranteed to meet or exceed PCMCIA 2.1 specifications.

Read Timing Diagram



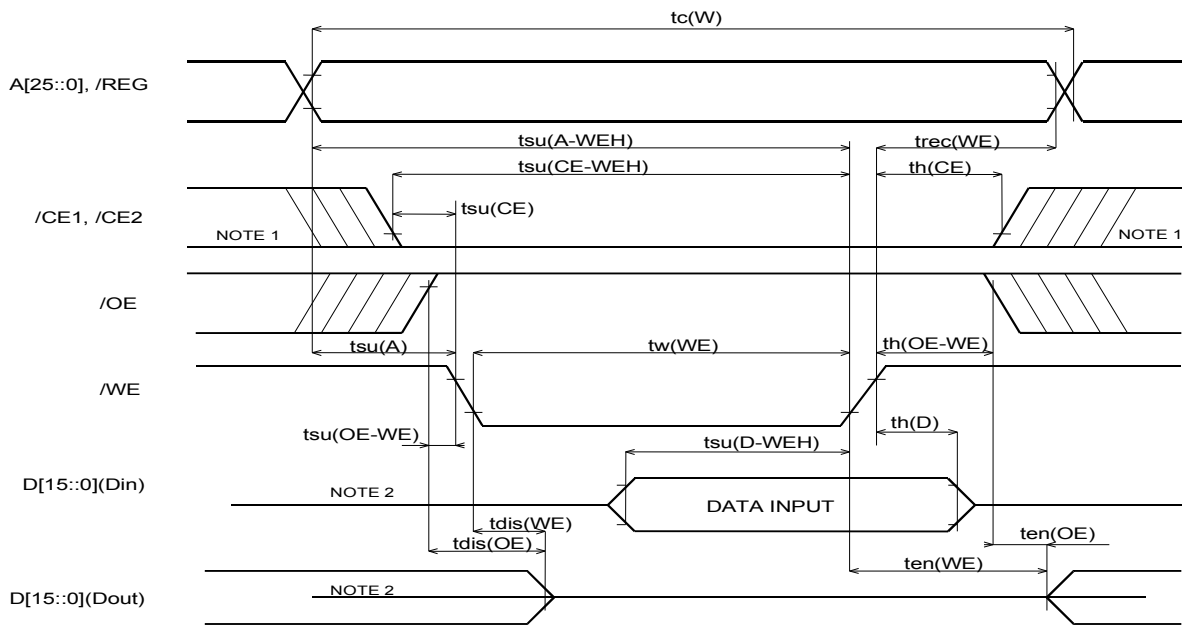
Note: Signal may be high or low in this area.

Write Timing Parameters

| SYMBOL (PCMCIA) | Parameter | 90ns | | Unit |
|------------------|---------------------------------|------|-----|------|
| | | Min | Max | |
| t_{cW} | Write Cycle Time | 90 | | ns |
| $t_{w(WE)}$ | Write Pulse Width | 80 | | ns |
| $t_{su(A)}$ | Address Setup Time | 20 | | ns |
| $t_{su(A-WEH)}$ | Address Setup Time for WE# | 100 | | ns |
| $t_{su(CE-WEH)}$ | Card Enable Setup Time for WE# | 100 | | ns |
| $t_{su(D-WEH)}$ | Data Setup Time for WE# | 50 | | ns |
| $t_h(D)$ | Data Hold Time | 20 | | ns |
| $t_{rec(WE)}$ | Write Recover Time | 20 | | ns |
| $t_{dis(WE)}$ | Output Disable Time from WE# | | 75 | ns |
| $t_{dis(OE)}$ | Output Disable Time from OE# | | 75 | ns |
| $t_{en(WE)}$ | Output Enable Time from WE# | 5 | | ns |
| $t_{en(OE)}$ | Output Enable Time from OE# | 5 | | ns |
| $t_{su(OE-WE)}$ | Output Enable Setup from WE# | 10 | | ns |
| $t_h(OE-WE)$ | Output Enable Hold from WE# | 10 | | ns |
| $t_{su(CE)}$ | Card Enable Setup Time from OE# | 0 | | ns |
| $t_h(CE)$ | Card Enable Hold Time | 20 | | ns |

Note: AC timing diagrams and characteristics are guaranteed to meet or exceed PCMCIA 2.1 specifications.

Write Timing Diagram



Notes:

- Signal may be high or low in this area
- When the data I/O pins are in the output state, no signals shall be applied to the data pins (D15 - D0) by the host system.

Data Write and Erase Performance ^(1,3)

VCC = 5V ± 5%, T_A = 0C to + 70C

| Symbol | Parameter | Notes | Min | Typ ⁽¹⁾ | Max | Units |
|--------------------|------------------------|-----------|-----|--------------------|-----|-------|
| t _{WHQV1} | Word/Byte Program time | 4 | | 8 | | μs |
| t _{EHQV2} | Block Program Time | device S5 | 0.4 | 0.5 | | sec |
| | Block Erase Time | device S5 | 0.9 | 1.1 | | sec |

Notes:

1. Typical: Nominal voltages and T_A = 25C.
2. Excludes system overhead.
3. Valid for all speed options.
4. To maximize system performance RDY/BSY# signal should be polled.

Card Family and Version Information

| | |
|----------------------|-----------|
| FL16-090-02M-11189S5 | 2 MBYTES |
| FL16-090-04M-11189S5 | 4 MBYTES |
| FL16-090-08M-11189S5 | 8 MBYTES |
| FL16-090-16M-11189S5 | 16 MBYTES |

Similar range of FLASH Card using AMD memory devices also available from **CardPro™ International**

CardPro™ International

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